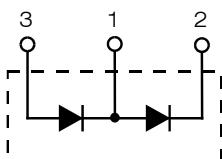


Diode Modules

PSKD 310

Preliminary Data Sheet

V_{RSM}	V_{RRM}	Type
V	V	
900	800	PSKD 310/08
1300	1200	PSKD 310/12
1500	1400	PSKD 310/14
1700	1600	PSKD 310/16
1900	1800	PSKD 310/18



I_{FRMS} = 2x 480 A
 I_{FAVM} = 2x 305 A
 V_{RRM} = 800-1800 V



Symbol	Test Conditions	Maximum Ratings	
I_{FRMS}	$T_{VJ} = T_{VJM}$	480	A
I_{FAVM}	$T_c = 100^\circ\text{C}$; 180° sine	305	A
I_{FSM}	$T_{VJ} = 45^\circ\text{C}$; $V_R = 0$	11 500	A
	$t = 10 \text{ ms (50 Hz), sine}$ $t = 8.3 \text{ ms (60 Hz), sine}$	12 200	A
	$T_{VJ} = T_{VJM}$ $V_R = 0$	9 600	A
	$t = 10 \text{ ms (50 Hz), sine}$ $t = 8.3 \text{ ms (60 Hz), sine}$	10 200	A
$\int i^2 dt$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	662 000	A^2s
	$t = 10 \text{ ms (50 Hz), sine}$ $t = 8.3 \text{ ms (60 Hz), sine}$	620 000	A^2s
	$T_{VJ} = T_{VJM}$ $V_R = 0$	460 000	A^2s
	$t = 10 \text{ ms (50 Hz), sine}$ $t = 8.3 \text{ ms (60 Hz), sine}$	430 000	A^2s
T_{VJ}		-40...+150	$^\circ\text{C}$
T_{VJM}		150	$^\circ\text{C}$
T_{stg}		-40...+125	$^\circ\text{C}$
V_{ISOL}	50/60 Hz, RMS	3000	$\text{V}\sim$
	$I_{ISOL} \leq 1 \text{ mA}$	3600	$\text{V}\sim$
M_d	Mounting torque (M5) Terminal connection torque (M8)	2.5-5/22-44 Nm/lb.in. 12-15/106-132 Nm/lb.in.	
Weight	Typical including screws	320	g

Symbol	Test Conditions	Characteristic Values	
I_{RRM}	$T_{VJ} = T_{VJM}$; $V_R = V_{RRM}$	40	mA
V_F	$I_F = 600 \text{ A}$; $T_{VJ} = 25^\circ\text{C}$	1.2	V
V_{T0}	For power-loss calculations only	0.75	V
r_T	$T_{VJ} = T_{VJM}$	0.63	$\text{m}\Omega$
R_{thJC}	per diode; DC current	0.129	K/W
	per module	0.065	K/W
R_{thJK}	per diode; DC current	0.169	K/W
	per module	0.0845	K/W
Q_s	$T_{VJ} = 125^\circ\text{C}$, $I_F = 400 \text{ A}$; $-di/dt = 50 \text{ A}/\mu\text{s}$	760	μC
I_{RM}		275	A
d_s	Creepage distance on surface	12.7	mm
d_A	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

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Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.

Features

- Direct copper bonded Al_2O_3 -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 $\text{V}\sim$
- UL registered, E 148688

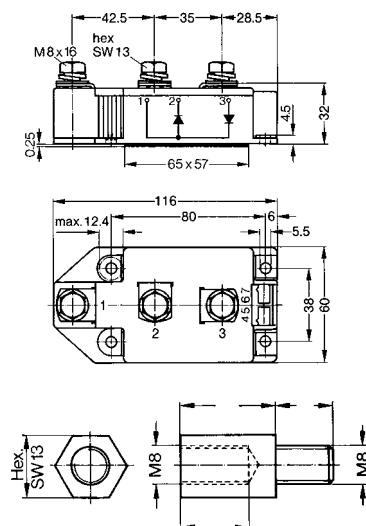
Applications

- Supplies for DC power equipment
- DC supply for PWM inverter
- Field supply for DC motors
- Battery DC power supplies

Advantages

- Space and weight savings
- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Dimensions in mm (1 mm = 0.0394")



Threaded spacer for higher Anode/Cathode construction: Type **ZY 250**, material brass

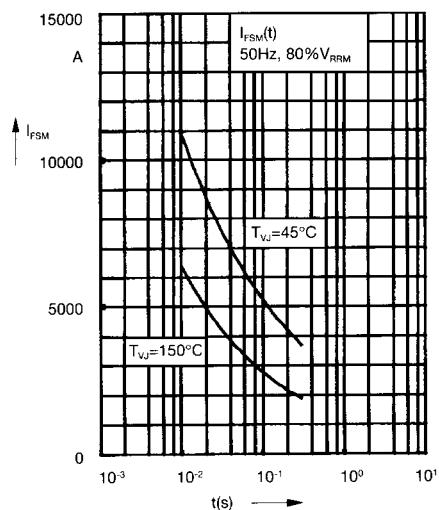


Fig. 1 Surge overload current
 I_{FSM} : Crest value, t: duration

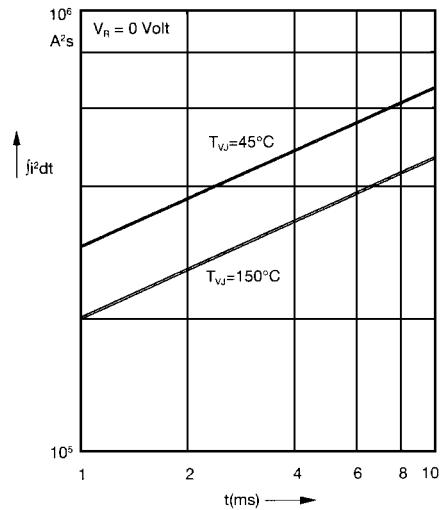


Fig. 2 $\int i^2 dt$ versus time (1-10 ms)

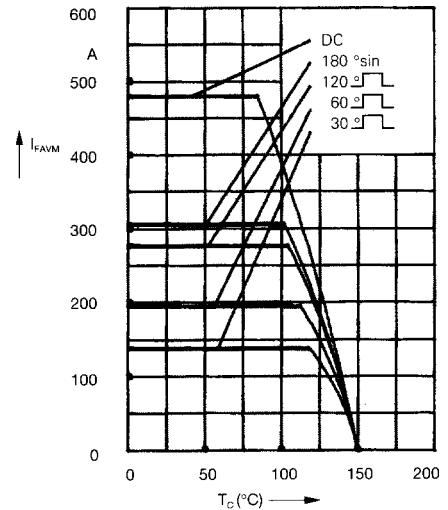


Fig. 2a Maximum forward current
at case temperature

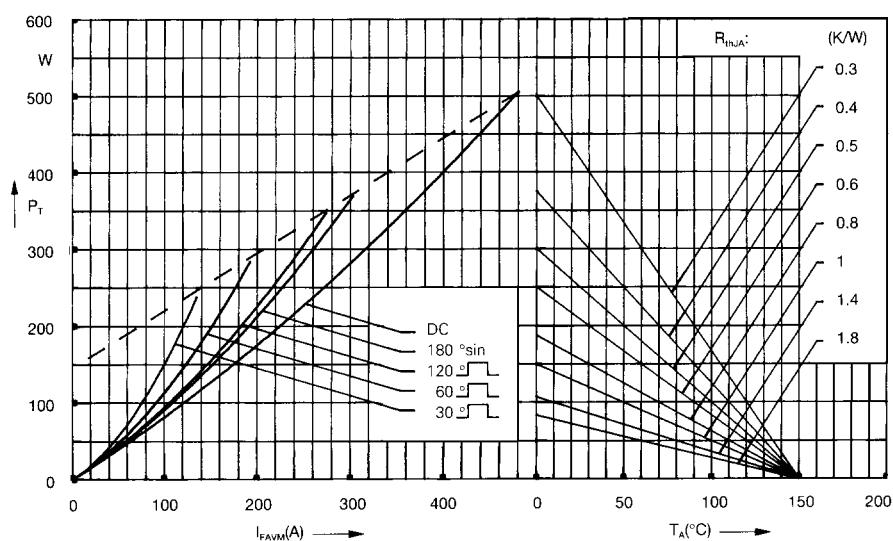


Fig. 3 Power dissipation versus
forward current and ambient
temperature (per diode)

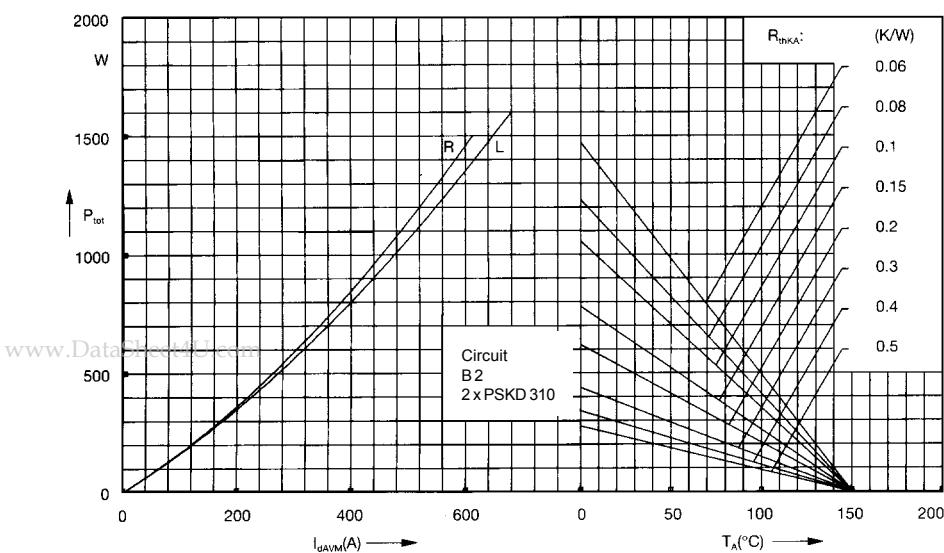


Fig. 4 Single phase rectifier bridge:
Power dissipation versus direct
output current and ambient
temperature
R = resistive load
L = inductive load

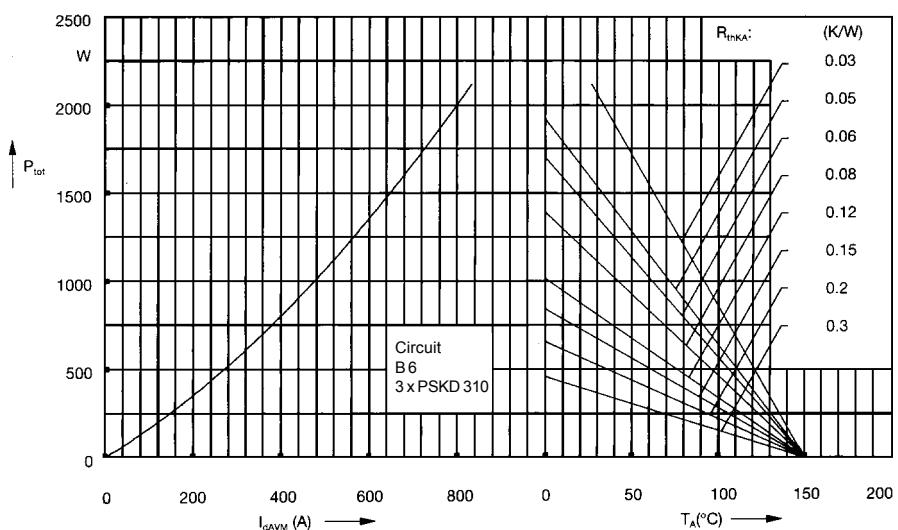


Fig. 5 Three phase rectifier bridge:
Power dissipation versus direct
output current and ambient
temperature

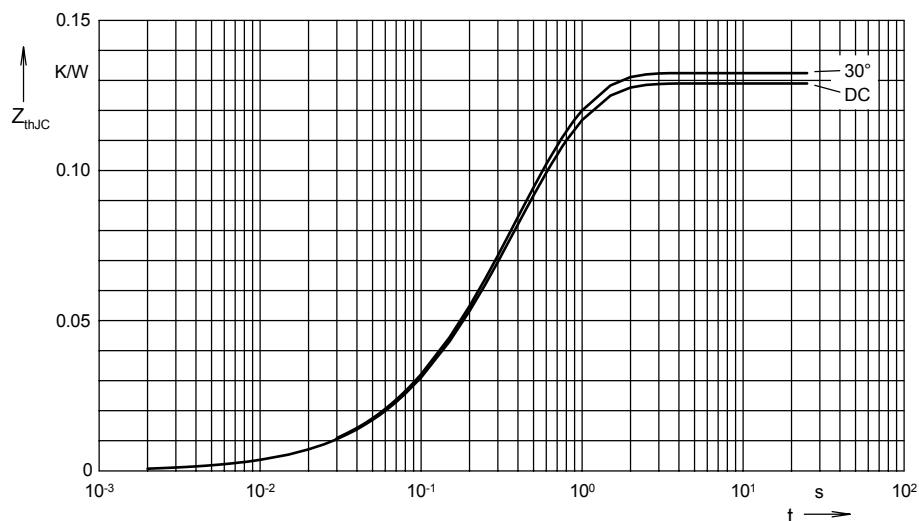


Fig. 6 Transient thermal impedance
junction to case (per diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.129
180°	0.131
120°	0.132
60°	0.132
30°	0.133

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0099
2	0.0165	0.168
3	0.1091	0.456

Fig. 7 Transient thermal impedance
junction to heatsink (per diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.169
180°	0.171
120°	0.172
60°	0.172
30°	0.173

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.0099
2	0.0165	0.168
3	0.1091	0.456
4	0.04	1.36